ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES®	PC. Bannockl	burn, Illinois, A	ll rights reserved utions.	under both	This docume level parts, t	ent is a declarati he declaration e	on of the su	bstances v s all lower	vithin the manufactu level materials for v	rer listed i which the r	tem. Note: nanufacture	if the item is an as er has engineering	sembly with low responsibility.	
			Form Type Distribute	e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater				ials and Mfg Information						
Supplier Information														
Company name* Comp			ompany unique ID			Unique ID Authority				Respon	Response Date*			
onsemi									2025-06-08					
ntact Name Title - Contact					Phone - Contact*				Email - Contact*					
Product-Env-Stewards Product Env			viro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Represe			entative			Phone - Representative*			Email - Representative*					
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Requester Item Number Mfr Iten		n Number Mfr Item Name				Effective Date	ve Date Version Manufacturing Site			Weight*	UOM	Unit Type		
	NSBA11	BA114EDXV6T1G SS SOT563 RSTR 2		R XSTR TR		2025-06-08 CN1		N1	2.72		mg	Each		
Ianufacturing Proccess Informat	ion						-							
Terminal Plating / Grid Array Ma	terial 7	ial Terminal Base Alloy		J-STD-020 MSI	SL Rating Peak		k Process Body Temperature Max Time at Peak		. Tempera	ure Num	ber of Reflow Cyc	les		
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30	secor	ids 3			
omments														
vel 1 - maximum time at peak temperatu	re during so	Idering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless	otherwise noted).							
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.06	mg	Supplier	Silicon (Si)	7440-21-3		0.06	mg
Lead Frame	1.18	mg	Supplier	Silver (Ag)	7440-22-4		0.21	mg
			В	Nickel (Ni)	7440-02-0		0.3646	mg
			Supplier	Iron (Fe)	7439-89-6		0.5039	mg
			Supplier	Copper (Cu)	7440-50-8		0.1015	mg
Mold Compound-Black	1.4	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.14	mg
			Supplier	Carbon Black (C)	1333-86-4		0.007	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.203	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.91	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.14	mg
Plating	0.06	mg	Supplier	Tin (Sn)	7440-31-5		0.06	mg
Wire Bond - Cu	0.02	mg	Supplier	Copper (Cu)	7440-50-8		0.02	mg